Multilayer Ceramic Chip Capacitors

1 of 3 Creation Date : April 11, 2017 (GMT)

C1005X5R1H103K050BB









TDK item description C1005X5R1H103KT****

Applications	Commercial Grade Please refer to Part No. CGA2B3X5R1H103K050BB for Automotive use.	
Feature	General General (Up to 50V)	
Series	C1005 [EIA 0402]	
Status	Production (Not Recommended for New Design)	



	Size	
Length(L)	1.00mm ±0.05mm	
Width(W)	0.50mm ±0.05mm	
Thickness(T)	0.50mm ±0.05mm	
Terminal Width(B)	0.10mm Min.	
Terminal Spacing(G)	0.30mm Min.	
Recommended Land Pattern (PA)	0.30mm to 0.50mm	
Recommended Land Pattern (PB)	0.35mm to 0.45mm	
Recommended Land Pattern (PC)	0.40mm to 0.60mm	

	Electrical Characteristics	
Capacitance	10nF ±10%	
Rated Voltage	50VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	10000ΜΩ	

	Other
Soldering Method	Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	10000pcs

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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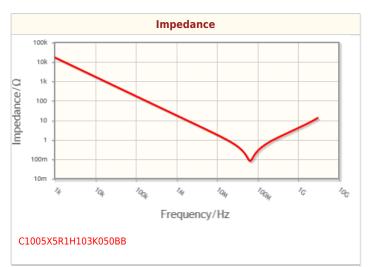


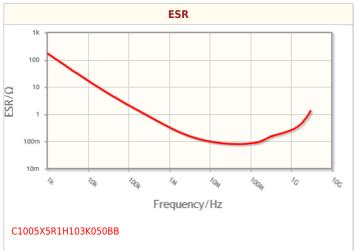


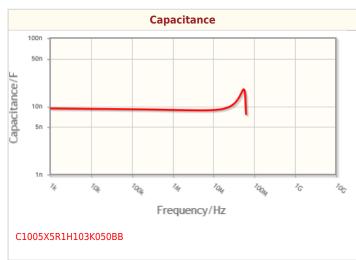


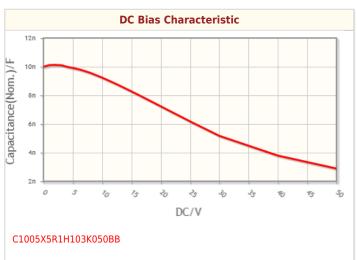


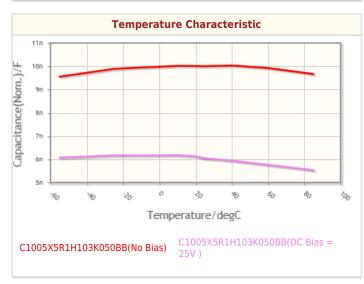
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

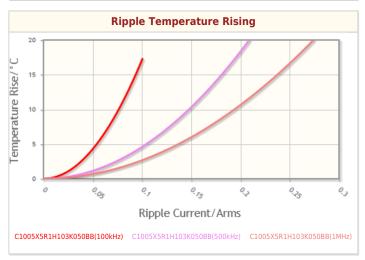












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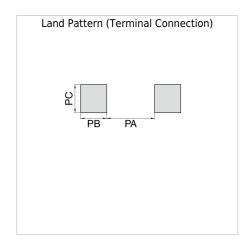






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Associated Images



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